



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C1R6BA3GNND

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1.6pF, 25V, ±0.1pF, C0G, 0201

A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>1R6</u> <u>B</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-la	ayer Ceramic Capacito	or			
② Size	0201 (inch c	code) L: 0.6	± 0.03 mm	W:	0.3 ± 0.03 n	nm
③ Dielect	ric C0G	8	Inner electrode)	Cu	
4 Capaci	tance 1.6 pF		Termination		Cu	
⑤ Capaci	tance ±0.1 pF		Plating		Sn 100% (Pb Free)
toleran	ce	9	Product		Normal	
6 Rated	Voltage 25 V	10	Special		Reserved for fu	iture use
7 Thickn	ess 0.3 ± 0.03	mm (f)	Packaging		Cardboard Tvp	e.13"reel(50.000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms
Q	432 min	
Insulation	More than 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.
Resistance		
Appearance	No abnormal exterior appearance	Visual inspection
Withstanding	No dielectric breakdown or	300% of the rated voltage
Voltage	mechanical breakdown	
Temperature	C0G	
Characteristics (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)		ge should be within ±30PPM/℃)
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.
of Termination	terminal electrode	
Bending Strength	Capacitance change: within ±0.5pF	Bending to the limit (1mm)
		with 1.0mm/sec.
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder
	is to be soldered newly	245±5℃, 3±0.3sec.
		(preheating : 80~120 ℃ for 10~30sec.)
Resistance to	Capacitance change : within ±0.25pF	Solder pot : 270±5℃, 10±1sec.
Soldering heat	Tan δ, IR : initial spec.	

	Performance	Test condition			
Vibration Test	Capacitance change: within ±0.25pF	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours × 3 direction (x, y, z)			
Moisture Capacitance change: within ±0.75pF		With rated voltage			
Resistance	Q: 105.33 min IR: More than $25 \text{M}\Omega \cdot \mu\text{F}$	40±2℃, 90~95%RH, 500+12/-0 hour			
High Temperature	Capacitance change: within ±0.3pF	With 200% of the rated voltage			
Resistance	Q: 216 min	Max. operating temperature			
	IR : More than $50 \mathrm{M}\Omega \cdot \mu \mathrm{F}$	1000+48/-0 hour			
Temperature	Capacitance change: within ±0.25pF	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperature $ ightarrow$ 25 $^{\circ}$			
		→ Max. operating temperature → 25°C			
		5 cycles test			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

 $^{^{\}star}$ For the more detail Specification, Please refer to the Samsung MLCC catalogue.